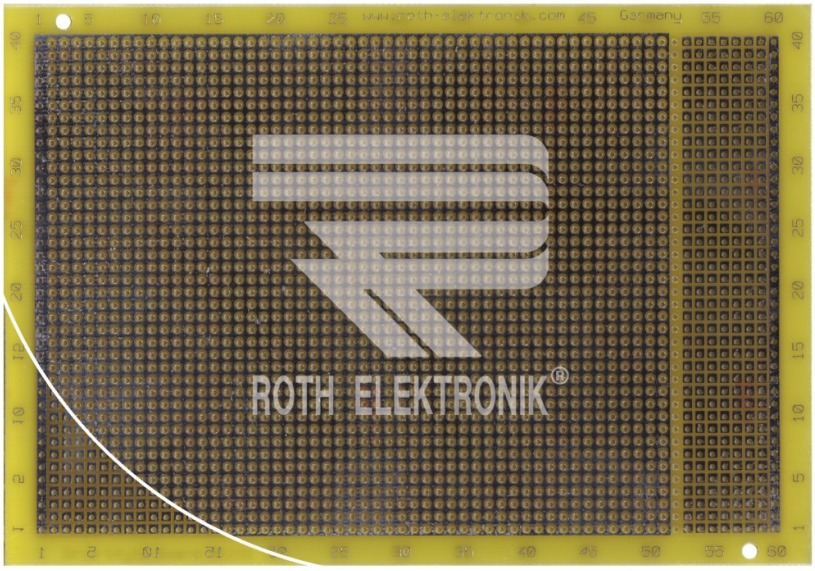
HF Prototyping Board (not in Europe-format)



RE231-LF

- EPOXY fibre-glass FR4 1.60 mm double-sided 35 µm CU (npt)
- solder side and component side hot air leveling (HAL-leadfree)

- hole spacing 2.54 mm x 2.54 mm
- 40 x 60 tracks of bored holes
- 40 x 58 square lands 2.00 mm²
- hole dia 1.02 mm (0.40")
- the component side is completely copper-clad, only the borings are cleared, so no componentcan be connected
- maximal screening effect of the electrical component side results when the cladding is connected to ground potential
- reliable HF, digital and analog circuits can be set up
- max. working temperature 150° C
- size 114.30 mm x 165.10 mm (4.5" x 6.5")

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